



FORM PTO-1449	SERIAL NO. 10/802,664	CASE NO. 10599/130
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	FILING DATE March 17, 2004	GROUP ART UNIT 2827
(use several sheets if necessary)	APPLICANT(S): William E. McKinzie III et al.	

REFERENCE DESIGNATION U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	NAME	CLASS/ SUBCLASS	FILING DATE
TD	A1	5,870,274	February 9, 1999	Lucas		
TD	A2	5,079,069	January 7, 1992	Howard et al.		
TD	A3	5,010,641	April 30, 1991	Sisler		

FOREIGN PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER <small>Number-Kind Code (if known)</small>	DATE	COUNTRY	CLASS/ SUBCLASS	TRANSLATION YES OR NO

OTHER ART – NON PATENT LITERATURE DOCUMENTS

EXAMINER INITIAL		(Include name of author, title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date page(s), volume-issue number(s), publisher, city and/or country where published.				
TD	A4	Ramesh Abhari and George V. Eleftheriades, "Suppression of the Parallel-Plate Noise in High Speed Circuits Using a Metallic Electromagnetic Band-Gap Structure," 2002 IEEE Microwave Theory and Techniques International Symposium, pp. 493-496.				
	A5	Telesphor Kamgaing and Omar M. Ramahi, "High-Impedance Electromagnetic Surfaces for Parallel-Plate Mode Suppression in High Speed Digital Systems," IEEE 11th Topical Meeting on Electrical Performance of Electronic Packaging, Oct 21-23, 2002, Monterey, CA, pp. 279-282.				
	A6	Telesphor Kamgaing and Omar M. Ramahi, "A Novel Power Plane with Integrated Simultaneous Switching Noise Mitigation Capability Using High Impedance Surface," IEEE Microwave and Wireless Components Letters, Vol. 13, No. 1, January 2003, pp. 21-23.				
	A7	S. Clavijo, R. Diaz, and W. McKinzie, "Design Methodology for Sievenpiper High-Impedance Surfaces: An Artificial Magnetic Conductor for Positive Gain Electrically Small Antennas." Submitted in Oct 2002 to the <i>IEEE Transactions on Antennas and Propagation</i> for publication in their Special Issue on Metamaterials. Publication date TBD.				
↓	A8	S. Van den Berghe, F. Olyslager, D. De Zutter, J. De Moerloose, and W. Temmerman, "Study of the Ground Bounce Caused by Power Plane Resonances," <i>IEEE Trans. Electromag. Compat.</i> , Vol. 40, No. 2, pp. 111-119, May 1998.				

EXAMINER /Thomas Dickey/	DATE CONSIDERED 01/23/2007
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EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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TD	A9	N. Na, J. Choi, S. Chun, M. Swaminathan, and J. Srinivasan, "Modeling and Transient Simulation of Planes in Electronic Packages," <i>IEEE Trans. Advanced Packaging</i> , Vol. 23, No. 3, pp. 340-352, August 2000.
	A10	S. Chun, M. Swaminathan, L. D. Smith, J. Srinivasan Z. Jin and M. K. Iyer, "Modeling of Simultaneous Switching Noise in High Speed Systems," <i>IEEE Trans. Advanced Packaging</i> , Vol. 24, No. 2, pp. 132-142, May 2001.
	A11	T. Tarvainen, "Simplified Modeling of Parallel Plate Resonances on Multilayer Printed Circuit Boards," <i>IEEE Trans. Electromag. Compat.</i> , Vol. 42, No. 3, pp. 284-289, August 2000.
	A12	A. R. Djordjevic and T. K. Sarkar, "An Investigation of Delta-I noise on Integrated Circuits," <i>IEEE Trans. Electromag. Compat.</i> , Vol. 35, No. 2, pp. 134-147, May 1993. [6] L. D. Smith, "Simultaneous Switch Noise and Power Plane Bounce for CMOS technology," <i>Proc. IEEE 8th Topical Meeting Elect. Perform. Electron. Packag.</i> , San Diego, CA, pp. 163-166, October 1999.
	A13	L. D. Smith, "Simultaneous Switch Noise and Power Plane Bounce for CMOS technology," <i>Proc. IEEE 8th Topical Meeting Elect. Perform. Electron. Packag.</i> , San Diego, CA, pp. 163-166, October 1999.
	A14	K. Lee and A. Barber, "Modeling and Analysis of Multichip Module Power Supply planes," <i>IEEE Trans. Comp., Packaging, Manuf., Tech.-PART B</i> , Vol. 18, No. 4, pp. 628-638, November 1995.
	A15	Edward R. Pillai, "Coax Via—A Technique to Reduce Crosstalk and Enhance Impedance Match at Vias in High-Frequency Multilayer Packages Verified by FDTD and MoM Modeling," <i>IEEE Trans. Microwave Theory Tech.</i> , Vol. 45, NO. 10, pp. 1981-1985, October 1997.
	A16	H. H. Wu, J. W. Meyer, K. Lee and A. Barber "Accurate Power Supply and Ground Plane Pair Models," <i>IEEE Trans. Advanced Packaging</i> , Vol. 22, No. 3, pp. 259-266, August 1999.
	A17	W. Pinello, A. C. Cangellaris and A. Ruehli, "Hybrid Electromagnetic Modeling of Noise Interactions in Packaged Electronics Based on the Partial-Element Equivalent Circuit Formulation," <i>IEEE Trans. Microwave Theory Tech.</i> , Vol. 45, No. 10, pp. 1889-1896, October 1997.
	A18	B. Archambeault and A. E. Ruehli, "Analysis of Power/Ground-plane EMI Decoupling Performance Using the Partial-Element Equivalent Circuit Technique," <i>IEEE Trans. Electromag. Compat.</i> , Vol. 43, No. 4, pp. 437-445, November 2001. Page 18 of 15119
	A19	M. Piket-May, A. Taflou and J. Baron, "FD-TD Modeling of Digital Signal Propagation in 3-D Circuits with Passive and Active Loads," <i>IEEE Trans. Microwave Theory Tech.</i> , Vol. 42, No. 8, pps. 1514-1523, August 1994.
	A20	R. Mittra, W. D. Becker and P. H. Harms, "A General Purpose Maxwell Solver for the Extraction of Equivalent Circuits of Electronic Package Components for Circuit Simulation," <i>IEEE Trans. Circuits and Systems-Part 1: Fundamental Theory and Applications</i> , Vol. 39, No. 11, pp. 964-973, November 1992.
↓	A21	T. H. Hubing, J. L. Drewniak, T. P. Van Doren and D. M. Hockason, "Power Bus Decoupling on Multilayer Printed Circuit Boards" <i>IEEE Trans. Electromag. Compat.</i> , Vol. 37, No. 2, pp. 155-166, May 1995.

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